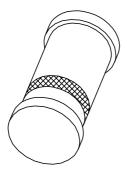
## DISCRETE SEMICONDUCTORS

# DATA SHEET



## BAV105 High-speed diode

Product specification Supersedes data of April 1996





### **High-speed diode**

**BAV105** 

#### **FEATURES**

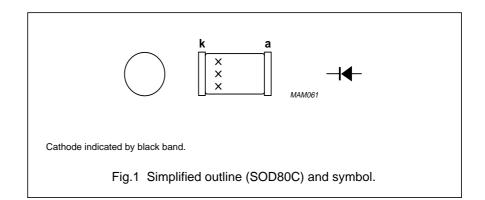
- Small hermetically sealed glass SMD package
- High switching speed: max. 6 ns
- · General application
- Continuous reverse voltage: max. 60 V
- Repetitive peak reverse voltage: max. 60 V
- Repetitive peak forward current: max. 600 mA.

#### **APPLICATIONS**

 High-speed switching in e.g. surface mounted circuits.

#### **DESCRIPTION**

The BAV105 is a high-speed switching diode fabricated in planar technology, and encapsulated in the small hermetically sealed glass SOD80C SMD package.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage		_	60	V
V <sub>R</sub>	continuous reverse voltage		_	60	V
I <sub>F</sub>	continuous forward current	see Fig.2; note 1	_	300	mA
I <sub>FRM</sub>	repetitive peak forward current		_	600	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; T <sub>j</sub> = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	9	A
		t = 100 μs	_	3	A
		t = 1 s	_	1	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; note 1	_	500	mW
T <sub>stg</sub>	storage temperature		-65	+200	°C
Tj	junction temperature		_	200	°C

#### Note

1. Device mounted on an FR4 printed-circuit board.

## High-speed diode

**BAV105** 

#### **ELECTRICAL CHARACTERISTICS**

 $T_j$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.3			
		I <sub>F</sub> = 10 mA	_	750	mV
		I <sub>F</sub> = 200 mA	_	1000	mV
		I <sub>F</sub> = 500 mA	_	1.25	V
		$I_F = 200 \text{ mA}; T_j = 100 ^{\circ}\text{C}$	_	950	mV
I <sub>R</sub>	reverse current	see Fig.5			
		V <sub>R</sub> = 60 V	_	100	nA
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 150 °C	_	100	μΑ
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 0; see Fig.6	_	2.5	pF
t <sub>rr</sub>	reverse recovery time	when switched from $I_F$ = 400 mA to $I_R$ = 400 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 40 mA; see Fig.7	_	6	ns
V <sub>fr</sub>	forward recovery voltage	when switched from $I_F = 400$ mA; $t_{r1} = 30$ ns; see Fig.8	_	2	V
		when switched from $I_F = 400$ mA; $t_{r2} = 100$ ns; see Fig.8	_	1.5	V

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point		300	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	350	K/W

#### Note

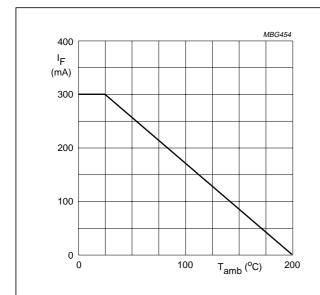
1. Device mounted on an FR4 printed-circuit board.

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## High-speed diode

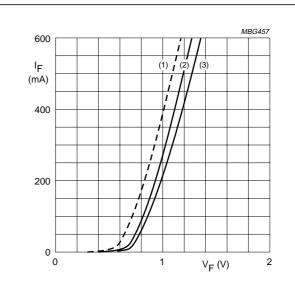
**BAV105** 

#### **GRAPHICAL DATA**



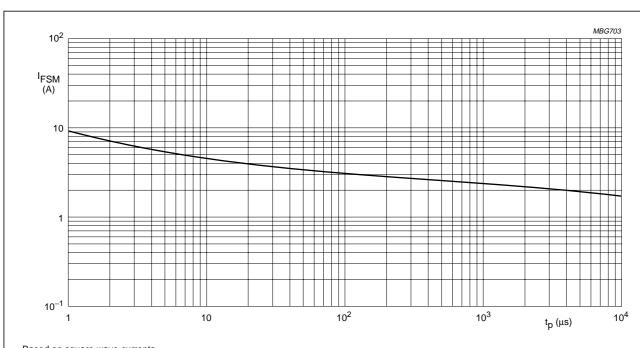
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1)  $T_j = 175 \,^{\circ}\text{C}$ ; typical values.
- (2)  $T_j = 25$  °C; typical values.
- (3)  $T_j = 25$  °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



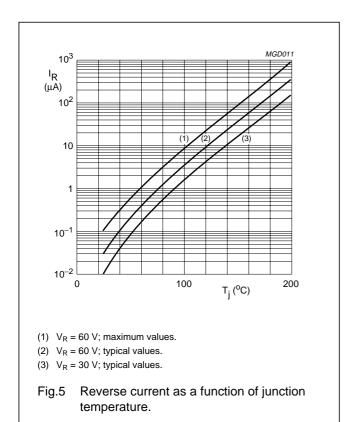
Based on square wave currents.  $T_j = 25$  °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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## High-speed diode

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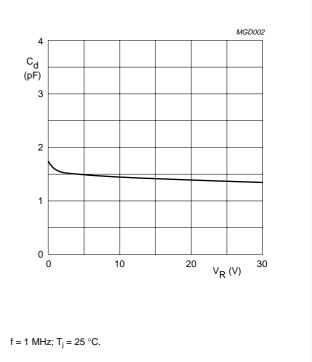
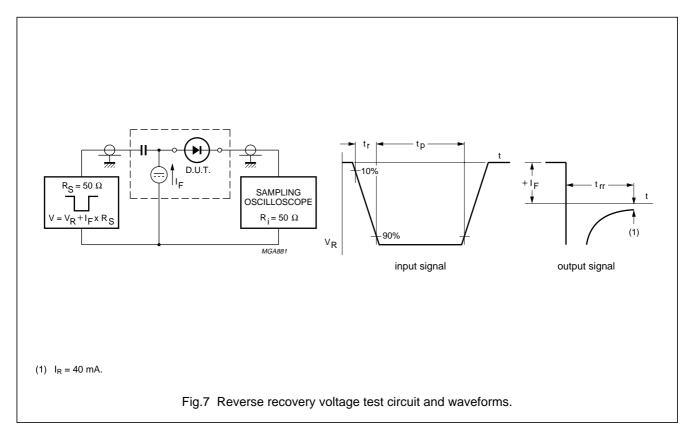
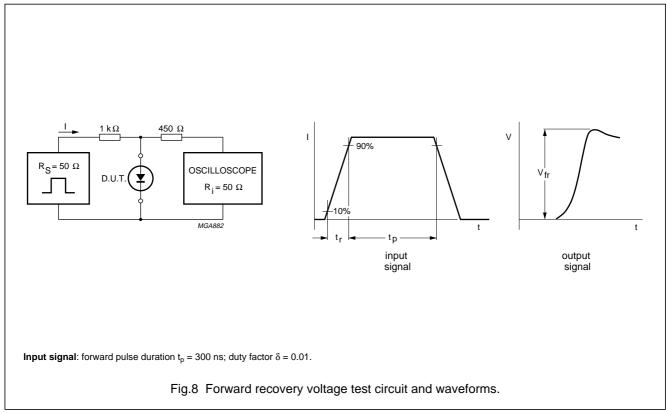


Fig.6 Diode capacitance as a function of reverse voltage; typical values.

## High-speed diode

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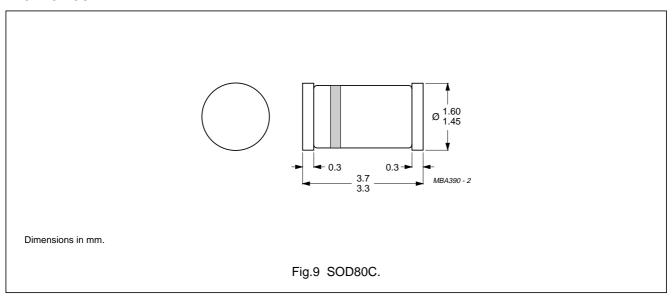


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#### High-speed diode

**BAV105** 

#### **PACKAGE OUTLINE**



#### **DEFINITIONS**

Data Sheet Status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		

#### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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